

What is claimed is:

1. A method of manufacturing a circuit board,  
comprising the steps of:  
forming a multilayered body, in which cable patterns on different layers insulated by an insulating layer are electrically connected, on a core substrate by a buildup process; and  
separating said multilayered body from said core substrate,  
wherein a metal layer is vacuum-adhered on said core substrate,  
said multilayered body is formed on said metal layer by the buildup process, and  
said multilayered body is separated from said core substrate together with said metal layer by breaking the vacuum state between said core substrate and said metal layer.
2. A method of manufacturing a circuit board,  
comprising the steps of:  
forming a multilayered body, in which cable patterns on different layers insulated by an insulating layer are electrically connected, on a core substrate by a buildup process; and  
separating said multilayered body from said core substrate,  
wherein a first metal layer is adhered on said core substrate,  
a second metal layer is vacuum-adhered on said first metal layer,  
said multilayered body is formed on said second metal layer by the buildup process, and  
said multilayered body is separated from said core substrate together with said second metal layer by breaking the vacuum state between said first metal layer and said second metal layer.

3. The method according to claim 2,  
wherein said second metal layer is broader than said first metal layer,  
an outer edge of said second metal layer, which is vacuum-adhered on  
said first metal layer, is adhered on said core substrate, and  
said multilayered body and said core substrate are cut at a position  
slightly shifted inward from an outer edge of said first metal layer so as to  
break the vacuum state between said first metal layer and said second metal  
layer, whereby said multilayered body is separated from said core substrate  
together with said second metal layer.
4. A method of manufacturing a circuit board,  
comprising the steps of:  
forming a multilayered body, in which cable patterns on different  
layers insulated by an insulating layer are electrically connected, on a core  
substrate by a buildup process;  
separating said multilayered body from said core substrate; and  
applying a prescribed treatment to said multilayered body which has  
been separated.